



PS7141-1A,PS7141L-1A

6-PIN DIP, 400V BREAK DOWN VOLTAGE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7141-1A and PS7141L-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7141L-1A has a surface mount type lead.

FEATURES

- 1 channel type (1 a output)
- Low LED operating current (IF = 2 mA)
- · Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7141L-1A: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8245/8246
- · CSA approved: No. CA 101391

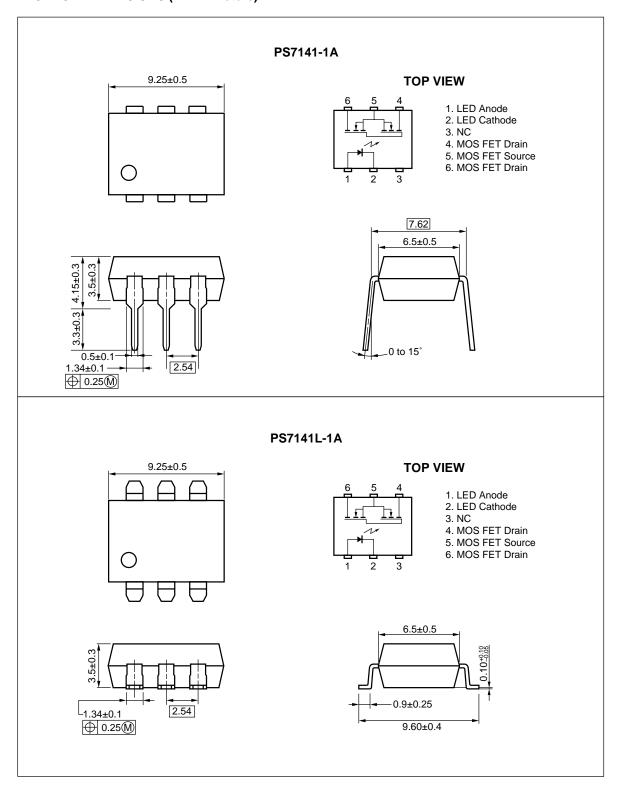
APPLICATIONS

- · Exchange equipment
- · Measurement equipment
- FA/OA equipment

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Date Published February 2003 CP(K)

PACKAGE DIMENSIONS (in millimeters)



ORDERING INFORMATION (Solder Contains Lead)

Part Number	Package	Packing Style	Application Part Number*1
PS7141-1A	6-pin DIP	Magazine case 50 pcs	PS7141-1A
PS7141L-1A			PS7141L-1A
PS7141L-1A-E3		Embossed Tape 1 000 pcs/reel	
PS7141L-1A-E4			

^{*1} For the application of the Safety Standard, following part number should be used.

ORDERING INFORMATION (Pb-Free)

Part Number	Package	Packing Style	Application Part Number*1
PS7141-1A-A	6-pin DIP	Magazine case 50 pcs	PS7141-1A
PS7141L-1A-A			PS7141L-1A
PS7141L-1A-E3-A		Embossed Tape 1 000 pcs/reel	
PS7141L-1A-E4-A			

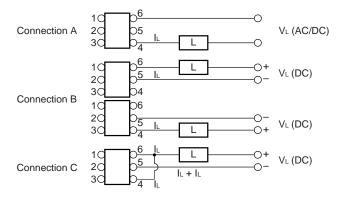
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		lF	50	mA
	Reverse Voltage		VR	5.0	V
	Power Dissipation		Po	50	mW
	Peak Forward Current*1		IFP	1	Α
MOS FET	Break Down Voltage	е	VL	400	V
	Continuous	Connection A	lι	150	mA
	Load Current*2	Connection B		200	
		Connection C		300	
	Pulse Load Current *3 (AC/DC Connection) Power Dissipation		ILP	300	mA
			P□	560	mW
Isolation Voltage *4			BV	1 500	Vr.m.s
Total Power Dissipation			P⊤	610	mW
Operating Ambient Temperature			TA	-40 to +85	°C
Storage Temperature			T _{stg}	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1 %

^{*2} Conditions: IF \geq 2 mA. The following types of load connections are available.



^{*3} PW = 100 ms, 1 shot

^{*4} AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

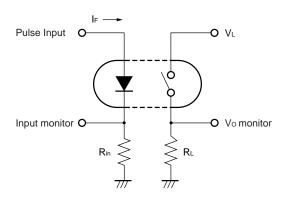
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

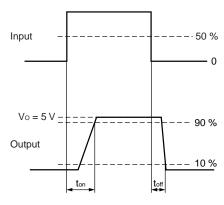
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

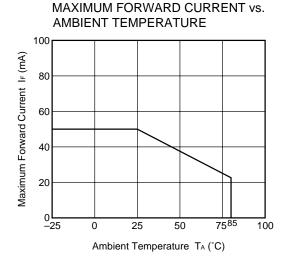
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lr	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	lLoff	V _D = 400 V		0.03	1.0	μΑ
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		65		pF
Coupled	LED On-state Current	I Fon	I _L = 150 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		20	30	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 150 \text{ mA}, t \le 10 \text{ ms}$		16	25	
	Turn-on Time *1	ton	If = 10 mA, Vo = 5 V, RL = 1.5 k Ω ,		0.35	1.0	ms
	Turn-off Time *1	toff	PW ≥ 10 ms		0.06	0.2	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF

*1 Test Circuit for Switching Time

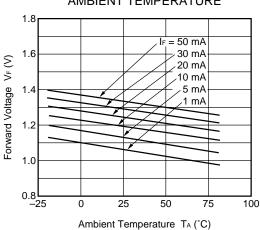




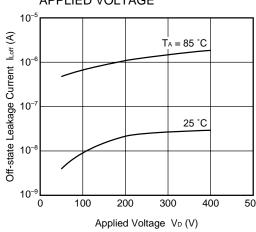
★ TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)



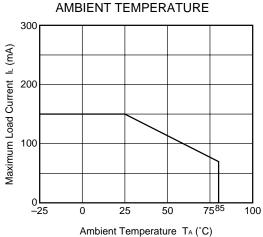




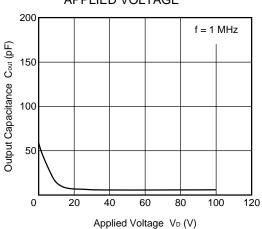
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



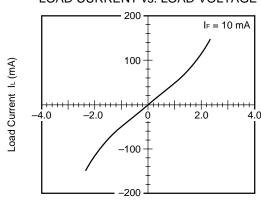
MAXIMUM LOAD CURRENT vs.



OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

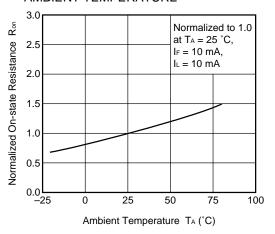


LOAD CURRENT vs. LOAD VOLTAGE

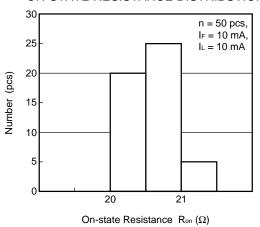


Load Voltage V_L (V)

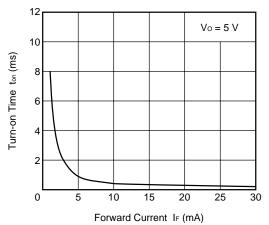
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



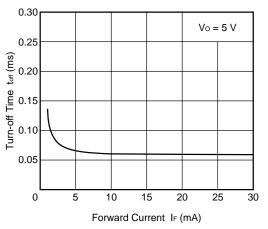
ON-STATE RESISTANCE DISTRIBUTION



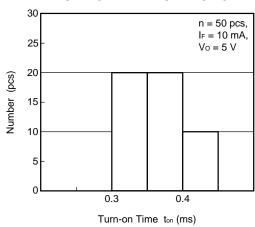
TURN-ON TIME vs. FORWARD CURRENT



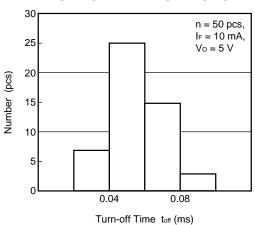
TURN-OFF TIME vs. FORWARD CURRENT



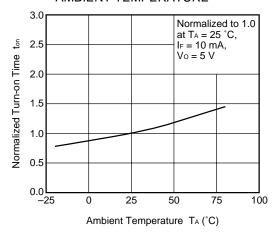
TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

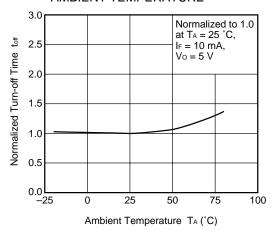


NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

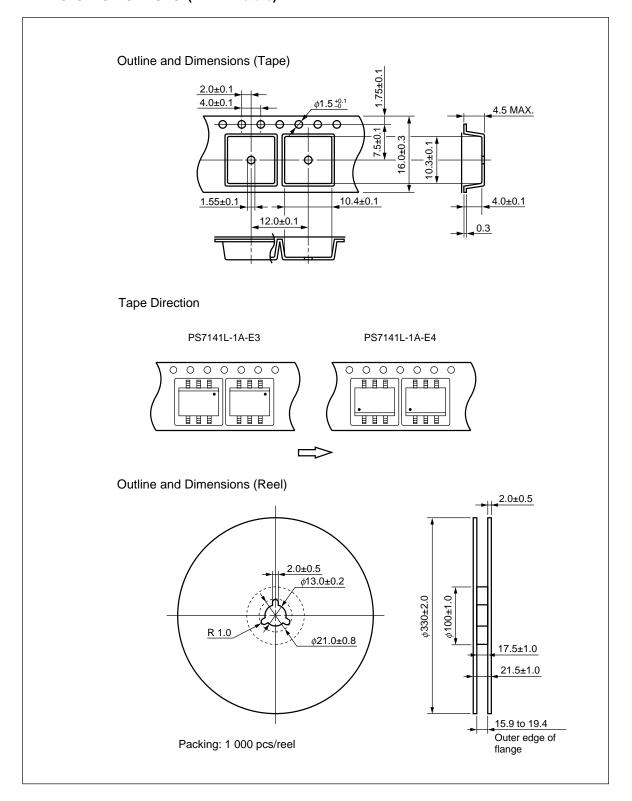


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



★ TAPING SPECIFICATIONS (in millimeters)



* RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

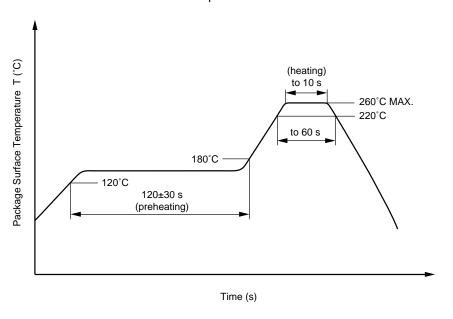
Time of peak reflow temperature
 Time of temperature higher than 220°C
 50 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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